AMENDMENTS TO THE CLAIMS

1. (Currently amended) A prepackaged semiconductor device assembly comprising:

a solder mask over a substrate;

a die;

conductive paths connecting contacts on said die with contacts in said substrate; and

~~a layer comprising at least one partially cured~~ an adhesive layer which is only partially cured for adhering said die to said solder mask.~~, said partially cured adhesive comprising one or more adhesive components that can cure at a temperature above ambient and at or below 100°C.~~

2. (Currently amended) The prepackaged semiconductor device assembly of claim 1, wherein said ~~partially cured~~ adhesive layer is at least fifty percent cured.

3. (Currently amended) The prepackaged semiconductor device assembly of claim 1, wherein said prepackaged assembly is encapsulated within a molded package and said adhesive is fully cured. ~~further comprising an encapsulant molded over the assembly.~~

Claims 4 and 5. (canceled)

6. (Currently amended) The prepackaged semiconductor device assembly of claim 1, wherein said ~~partially cured~~ adhesive layer comprises a material with a glassy temperature between about 5°C and about 20°C.

7. (Currently amended) The prepackaged semiconductor device assembly of claim 6, wherein said ~~partially cured~~ adhesive layer comprises bismaleimide.

8. (Currently amended) The prepackaged semiconductor device assembly of claim 7, wherein said ~~layer of partially cured~~ adhesive layer consists essentially of bismaleimide.

9. (Currently amended) The prepackaged semiconductor device assembly of claim 1, wherein said ~~partially cured~~ adhesive layer comprises initiators which react at a temperature below about 100°C.

10. (canceled)

11. (Currently amended) The prepackaged semiconductor device assembly of claim 1, wherein said contacts are substantially free of contaminants outgassed from said solder mask.

12. (Currently amended) A prepackaged semiconductor device assembly comprising:

a solder mask on a substrate;

a die;

electrical contacts on said substrate and said die, each ~~said~~ contact on said die being connected to a respective ~~said~~ contact on said substrate, said electrical contacts being devoid of contamination caused by outgassing from said solder mask; and

~~a layer comprising~~ ~~a partially-cured~~ an adhesive layer which is only partially cross-linked affixing said die to said solder mask.~~, said partially-cured adhesive containing one or more adhesive components that have curing temperatures above ambient and at or below 100°C.~~

13. (canceled)

14. (Currently amended) The prepackaged semiconductor device assembly of claim 12, wherein said ~~partially-cured~~ adhesive layer is at least fifty percent cross-linked. ~~cured.~~

15. (canceled)

16. (Currently amended) The prepackaged semiconductor device assembly of claim 12, wherein said ~~partially-cured~~ adhesive layer comprises a material with a glassy temperature between about 5°C and about 20°C.

17. (Currently amended) The prepackaged semiconductor device assembly of claim 16, wherein said ~~partially-cured~~ adhesive layer comprises bismaleimide.

18. (Previously presented) The prepackaged semiconductor device assembly of claim 16, wherein said ~~layer of partially-cured~~ adhesive layer consists essentially of bismaleimide.

19. (Currently amended) The prepackaged semiconductor device assembly of claim 12, wherein said ~~partially-cured~~ adhesive layer comprises initiators which react at a temperature below about 100°C.

20. (Currently amended) The prepackaged semiconductor device assembly of claim 12, wherein said contacts remain relatively free of contaminants released by outgassing from the solder mask during a cure process.

Claims 21-33. (canceled)

34. (Currently amended) The prepackaged semiconductor device assembly of claim 1, wherein said ~~layer of partially-cured~~ adhesive layer includes a resin bismaleimide.

35. (canceled)

36. (Currently amended) The prepackaged semiconductor device assembly of claim 12, wherein said ~~layer of partially-cured~~ adhesive layer includes a resin bismaleimide.

37. (Canceled)

38. (Currently amended) The prepackaged semiconductor device assembly of claim 1 [[12, wherein]] further comprising wire bonds connecting respective contacts on said substrate

and said die. ~~each said contact on said die is connected to said respective said contact on said substrate using wire bonds.~~

39. (Currently amended) The prepackaged semiconductor device assembly of claim 1, wherein said ~~partially cured~~ adhesive layer has adhesive strength sufficient to hold said die to said solder mask during subsequent package assembly processing selected from the group consisting of encapsulation, solder reflow, and testing.

40. (Currently amended) The prepackaged semiconductor device assembly of claim 12, wherein said ~~partially cured~~ adhesive layer has ~~having~~ adhesive strength sufficient to hold said die to said solder mask during subsequent package assembly processing selected from the group consisting of encapsulation, solder reflow, and testing.

41. (Previously presented) The prepackaged semiconductor device assembly of claim 1, wherein said adhesive layer contacts mutually facing surfaces of said die and said solder mask.

42. (Currently amended) The prepackaged semiconductor device assembly of claim 1, wherein said adhesive layer comprises one or more adhesive components including ~~includes~~ uncured component material.

43-45. (Canceled)

46. (Currently amended) The prepackaged semiconductor device assembly of claim 12, wherein said adhesive layer contacts mutually facing surfaces of said die and said solder mask.

47-50. (Canceled)

51. (New) The prepackaged semiconductor device assembly of claim 12, wherein said prepackaged assembly is encapsulated within a molded package and said adhesive is fully cured.